ABOCIATION CONNECTING LECTRONICS INDUSTRIES® INTERNATIONAL OF AN AND A CONNECTING	Bannockbu	irn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration entite decl	on of the su acompasses	bstances v all lower	vithin the manufactur level materials for w	rer listed it hich the m	em. Note:	if the item is an as r has engineering	sembly with lower responsibility.
	.1 IPC Web Site for Information on IPC-1752 Standard Form Dist				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M					als and M	fg Informat	ion	
Supplier Information													
Company name* Company			pany unique ID			Unique ID Authority				Response Date*			
semi								2024-06-01					
Contact Name	ne Title - Contact				-	Phone - Contact*				Email - Contact*			
oduct-Env-Stewards Product Enviro Con			o Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			entative	ntative I			Phone - Representative*			Email - Representative*			
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version Manufacturing Site		7	Weight*	UOM	Unit Type	
	NVTFS50 AG	TFS5C466NLWFT AFSM T6 40V		L u8FL WF		2024-06-01		М	MY1		30.365	mg	Each
Manufacturing Proccess Information	n												
Terminal Plating / Grid Array Materi	al Terminal Base Allo		lloy	J-STD-020 MSL Rating		Peak Proce	k Process Body Temperatur		ure Max Time at Peak Tempera		ure Num	ber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy		U Alloy		1		260		С	30	secon	ds 3		
Comments													
level 1 - maximum time at peak temperature o	during sold	lering is 10-3	) seconds										
For more information regarding material con	position p	lease refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0005	mg
			Supplier	Iron (Fe)	7439-89-6		0.0089	mg
			Supplier	Copper (Cu)	7440-50-8		0.3705	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Solder	1.65	mg	Supplier	Silver (Ag)	7440-22-4		0.0413	mg
			А	Lead (Pb)	7439-92-1	7a	1.5263	mg
			Supplier	Tin (Sn)	7440-31-5		0.0825	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0074	mg
			Supplier	Iron (Fe)	7439-89-6		0.0124	mg
			Supplier	Copper (Cu)	7440-50-8		12.3864	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg
Wire Bond - Cu	0.025	mg	Supplier	Copper (Cu)	7440-50-8		0.025	mg